

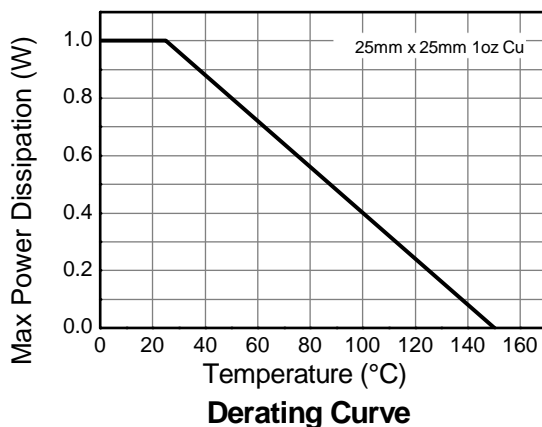
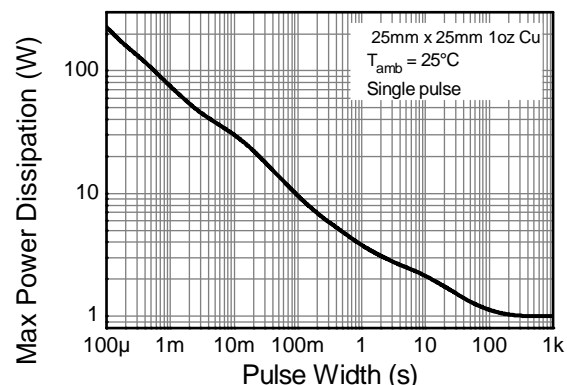
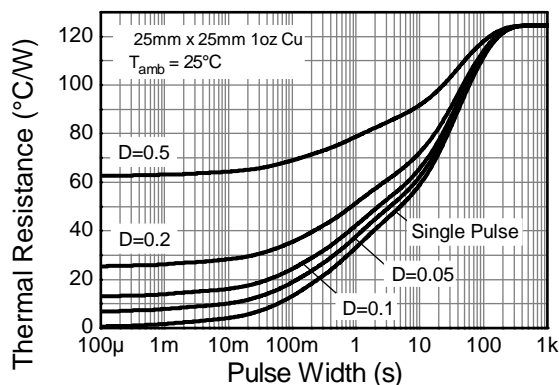
Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	80	V
Collector-Emitter Voltage	V _{CEO}	60	V
Emitter-Base Voltage	V _{EBO}	5	V
Collector Current	I _C	3	A
Peak Pulse Collector Current	I _{CM}	6	A
Base Current	I _B	500	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	1	W
Thermal Resistance, Junction to Ambient Air (Note 5)	R _{θJA}	125	°C/W
Thermal Resistance, Junction to Leads (Note 6)	R _{θJL}	18.2	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

- Notes:
- For a device surface mounted on 25mm X 25mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 - Thermal resistance from junction to solder-point (on the exposed collector pad).

Thermal Characteristics and Derating Information


Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
OFF CHARACTERISTICS (Note 7)						
Collector-Base Breakdown Voltage	BV_{CBO}	80	—	—	V	$I_C = 100\mu\text{A}$, $I_E = 0$
Collector-Emitter Breakdown Voltage	BV_{CEO}	60	—	—	V	$I_C = 10\text{mA}$, $I_B = 0$
Emitter-Base Breakdown Voltage	BV_{EBO}	5	—	—	V	$I_E = 100\mu\text{A}$, $I_C = 0$
Collector-Base Cutoff Current	I_{CBO}	—	—	0.1 10	μA	$V_{CB} = 60\text{V}$, $I_E = 0$ $V_{CB} = 60\text{V}$, $I_E = 0$, $T_A = +100^\circ\text{C}$
Emitter-Base Cutoff Current	I_{EBO}	—	—	0.1	μA	$V_{EB} = 4\text{V}$, $I_C = 0$
ON CHARACTERISTICS (Note 7)						
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	—	0.08 0.23	0.3 0.6	V	$I_C = 1\text{A}$, $I_B = 100\text{mA}$ $I_C = 3\text{A}$, $I_B = 300\text{mA}$
Base-Emitter Saturation Voltage	$V_{BE(sat)}$	—	0.85	1.25	V	$I_C = 1\text{A}$, $I_B = 100\text{mA}$
Base-Emitter Turn-On Voltage	$V_{BE(on)}$	—	0.8	1	V	$V_{CE} = 2\text{V}$, $I_C = 1\text{A}$
DC Current Gain	h_{FE}	70 100 80 40	200 200 185 120	— 300 — —	—	$V_{CE} = 2\text{V}$, $I_C = 50\text{mA}$ $V_{CE} = 2\text{V}$, $I_C = 500\text{mA}$ $V_{CE} = 2\text{V}$, $I_C = 1\text{A}$ $V_{CE} = 2\text{V}$, $I_C = 2\text{A}$
AC CHARACTERISTICS						
Transition Frequency	f_T	140	200	—	MHz	$V_{CE} = 5\text{V}$, $I_C = 100\text{mA}$, $f = 100\text{MHz}$
Output Capacitance	C_{obo}	—	—	30	pF	$V_{CB} = 10\text{V}$, $f = 1\text{MHz}$
Switching Times	t_{on} t_{off}	— —	35 230	— —	ns ns	$V_{CC} = 10\text{V}$, $I_C = 500\text{mA}$, $I_{B1} = I_{B2} = 50\text{mA}$

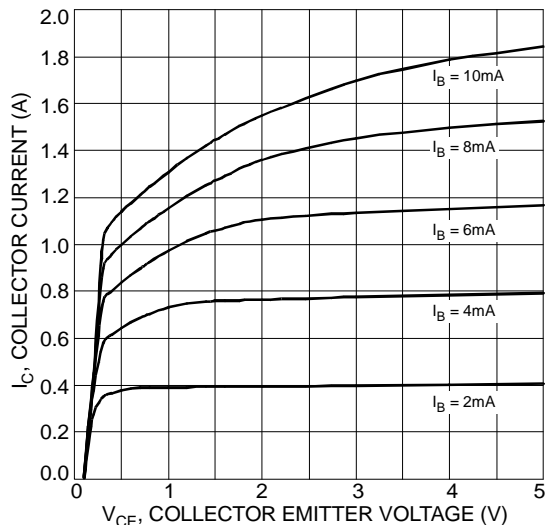
 Notes: 7. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.


Fig. 2 Typical Collector Current vs. Collector-Emitter Voltage

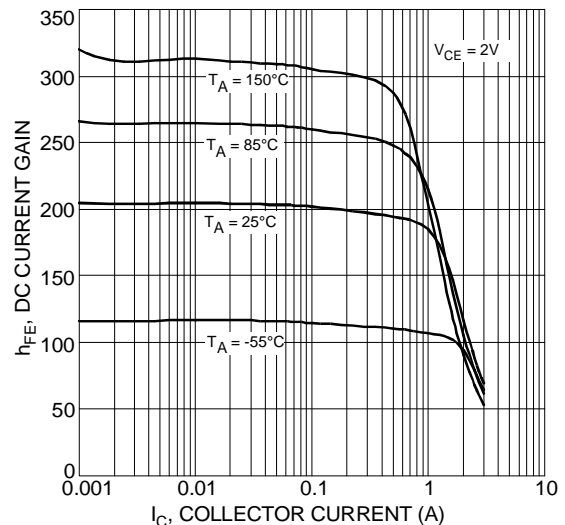


Fig. 3 Typical DC Current Gain vs. Collector Current

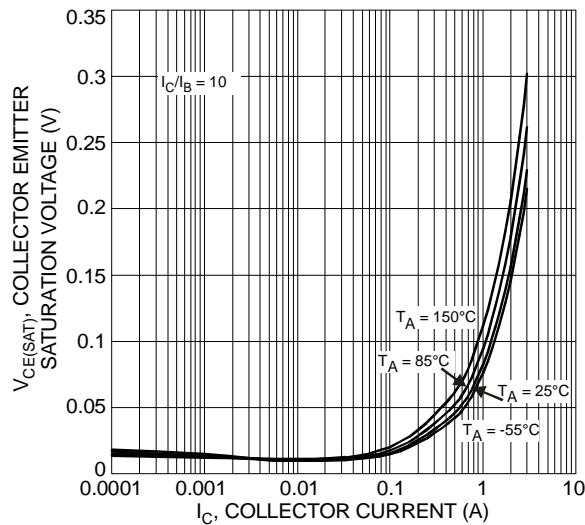


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

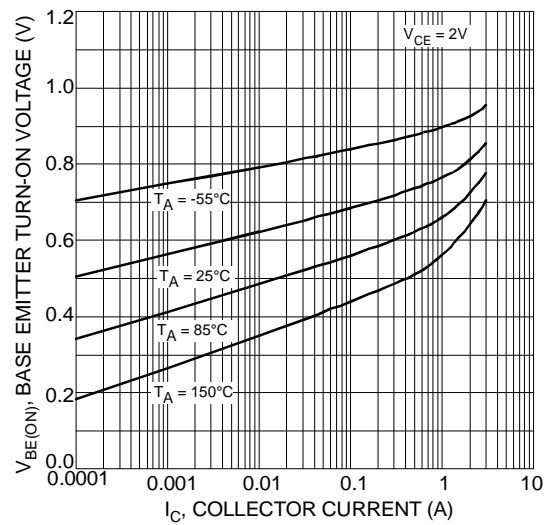


Fig. 5 Typical Base-Emitter Turn-On Voltage vs. Collector Current

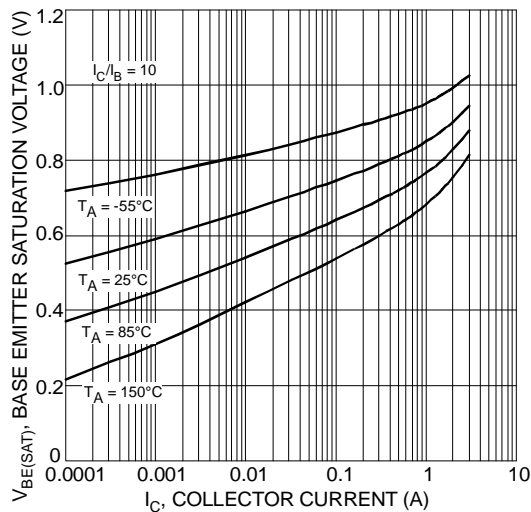


Fig. 6 Typical Base-Emitter Saturation Voltage vs. Collector Current

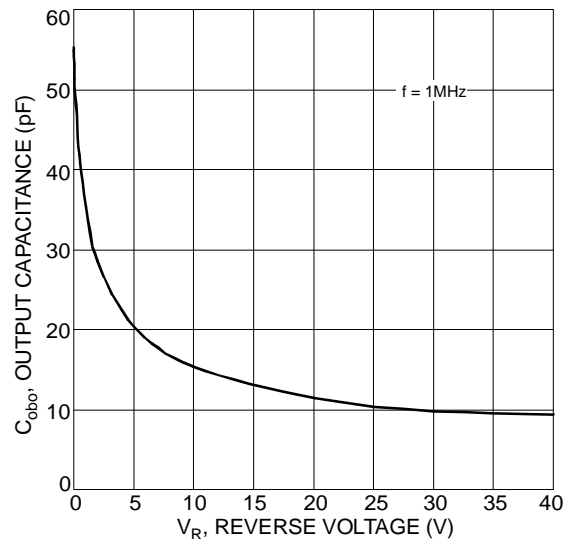


Fig. 7 Typical Output Capacitance Characteristics

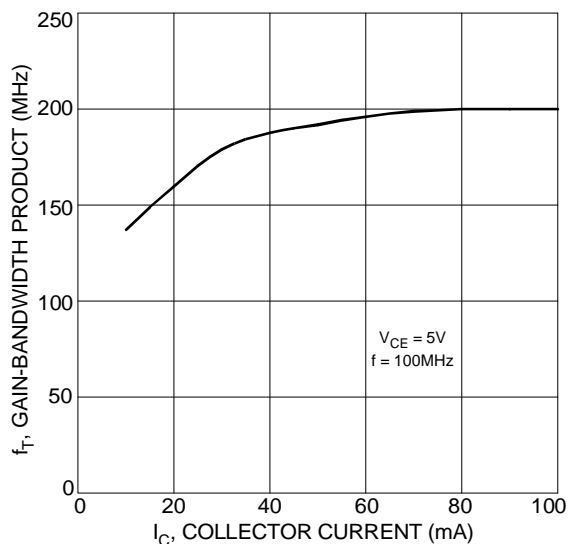
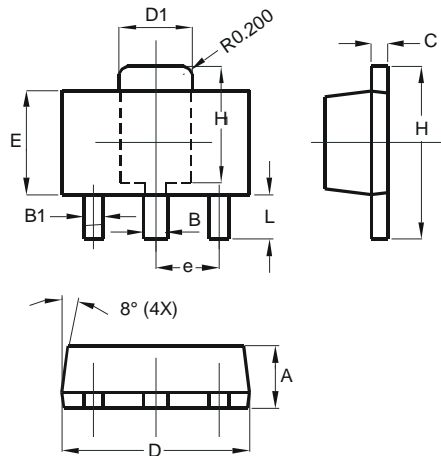


Fig. 8 Typical Gain-Bandwidth Product vs. Collector Current

Package Outline Dimensions

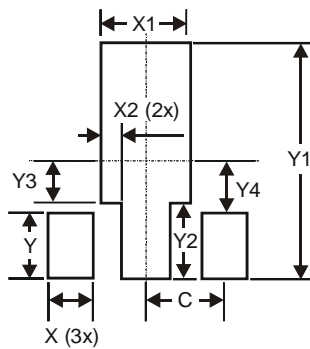
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT89		
Dim	Min	Max
A	1.40	1.60
B	0.44	0.62
B1	0.35	0.54
C	0.35	0.44
D	4.40	4.60
D1	1.62	1.83
E	2.29	2.60
e	1.50 Typ	
H	3.94	4.25
H1	2.63	2.93
L	0.89	1.20
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
X	0.900
X1	1.733
X2	0.416
Y	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
C	1.500

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